

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An apparatus for mounting a plurality of semiconductor devices on a wiring board, the apparatus comprising:

a compression bonding head relatively movable to a table on which the wiring board is placed, said compression bonding head having a holding means with a plurality of suction parts for sucking and holding ~~pressing chips and~~ said semiconductor devices thereon, wherein said suction parts are provided at the positions respectively corresponding to said semiconductor devices; and

a pressing chip held in the compression bonding head by the holding means for forming a concave area of a predetermined size in an insulating adhesive layer on said wiring board.

2-3. (Canceled)

4. (Currently Amended) The apparatus as claimed in claim 1, wherein said holding means are constructed as sucking the air via a plurality of suction holes ~~hole~~ formed in the compression bonding part of said compression bonding head.

5-10. (Canceled)

11. (New) The apparatus as claimed in claim 1, further comprising a press head for holding the pressing chip.

12. (New) The apparatus as claimed in claim 1, wherein the pressing chip has an outer size that is 1.5 to 0.5 times the outer size of the semiconductor device.

13. (New) The apparatus of claim 12, wherein the pressing chip is 1.0 to 0.7 times the outer size of the semiconductor device.